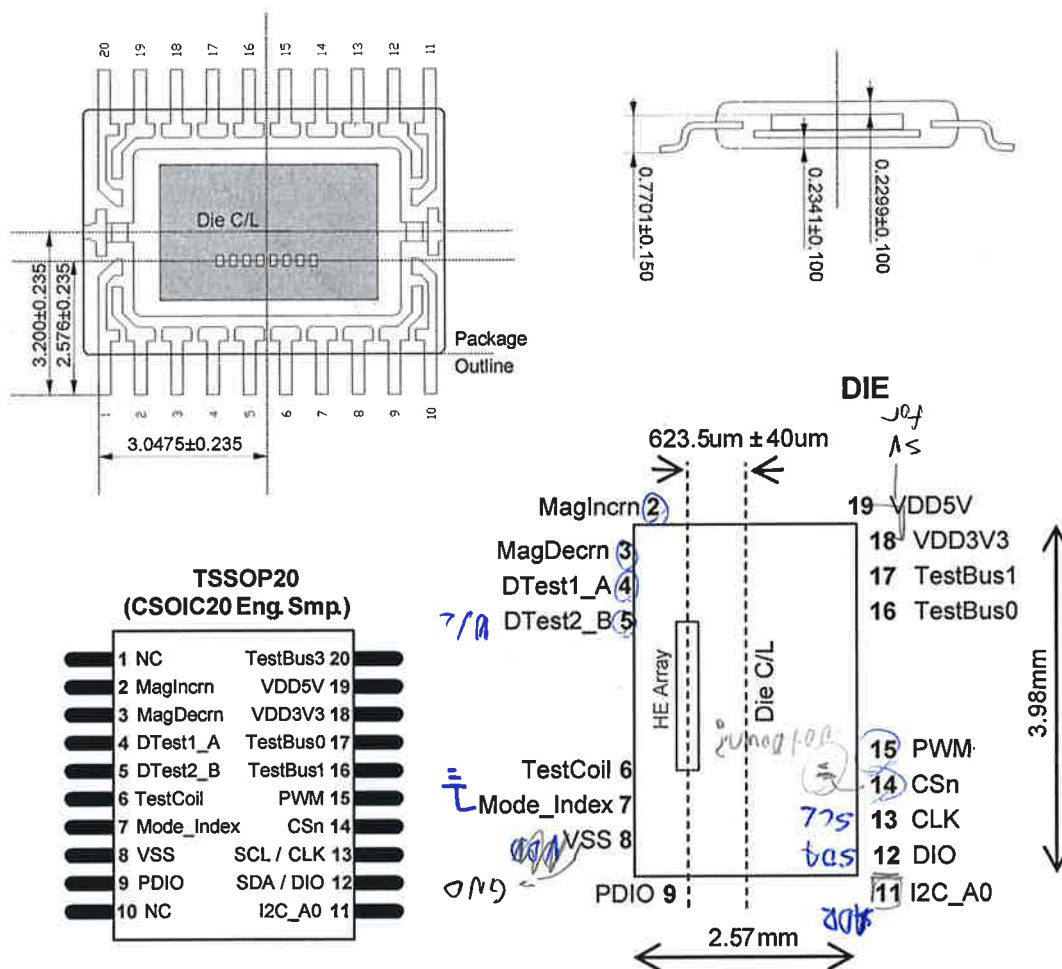


9 Package Drawings and Markings

Figure 14. 20-pin TSSOP Package

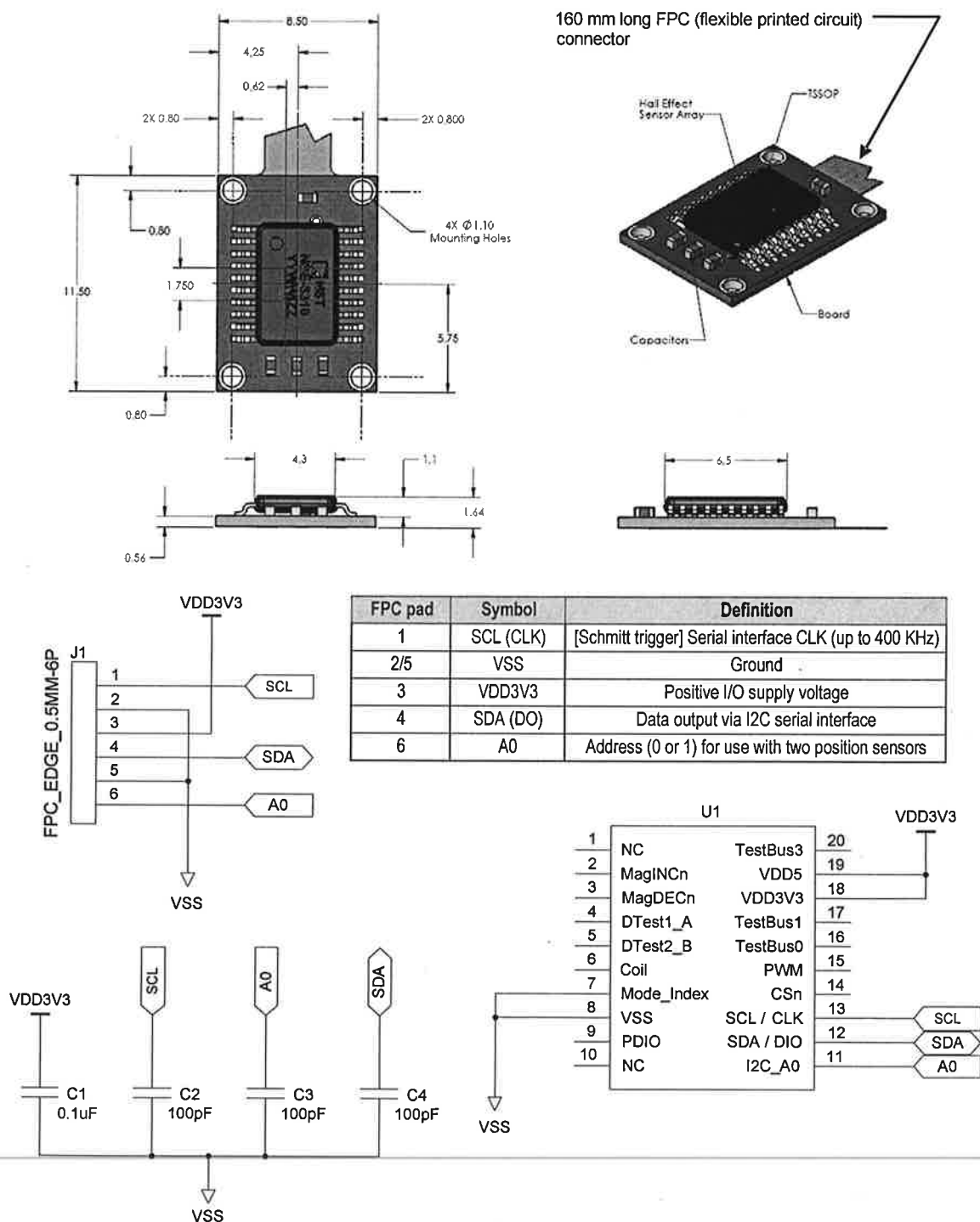


Pad Name	Coordinates	
	x	y
VDD	291.4	2418
VDDA	407.85	2418
TB0	717.2	2418
TB1	822.2	2418
PWM	2877.2	2418
CSn	3068.2	2418
CLK	3259.2	2418
DIO	3450.2	2418
I2C_A0	3641.2	2418
PDIO	3828	668.5
VSS	3526.75	52

Pad Name	Coordinates	
	x	y
VSS	3423.65	52
Mode_Index	3235.45	52
COIL	3132.35	52
DTEST2_B	720.6	52
DTEST1_A	383	52
MagDecrn	175.4	52
MagIncrn	52	1206.7
TB2	52	1321.7
TB3	52	1657.75
VDDHall	52	1772.7
VDD5V	52	2161

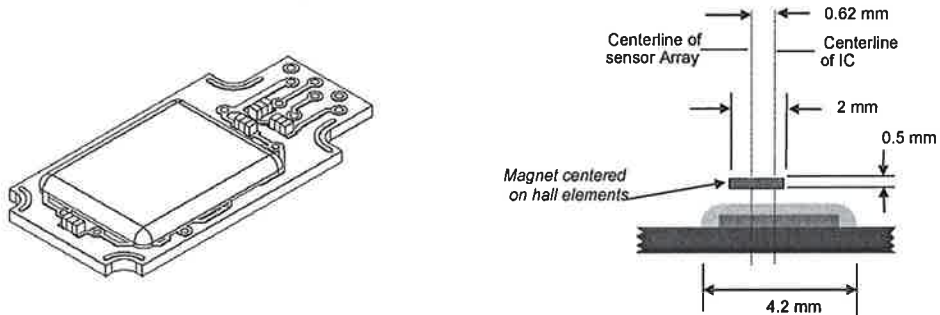
The evaluation kit includes an NSE-5310 mounted in a TSSOP 20 package with flex cable, for easy handling during evaluation and system development. The TRK-1T02-E evaluation pack includes a TRK-1T02 along with a suitable linear magnetic strip, a MC-31MB interface card and New Scale Pathway™ software with intuitive user interface to facilitate evaluation.

Figure 15. TRK-1T02 Package for Easy Handling During Evaluation



Custom chip-on-board packaging can be provided for qualified OEMs. Minimum order quantities apply. Inquire for more detail.

Figure 16. Custom Chip-On-Board Packaging (5.4 x 4.2 x 0.6 mm)



Custom wafer-level chip scale packaging can be provided for qualified OEMs. Minimum order quantities apply. Inquire for more detail.

Figure 17. Custom Wafer-Level Chip Scale Packaging (as small as 3.9 x 2.5 x 0.6 mm)

